



Product/Process Change Notice - PCN 20_0148 Rev. -

Analog Devices, Inc. Three Technology Way Norwood, Massachusetts 02062-9106

This notice is to inform you of a change that will be made to certain ADI products (see Appendix A) that you may have purchased in the last 2 years. **Any inquiries or requests with this PCN (additional data or samples) must be sent to ADI within 30 days of publication date.** ADI contact information is listed below.

PCN Title: HMC788A-EP Die Revision

Publication Date: 18-Mar-2020

Effectivity Date: 20-Jun-2020 *(the earliest date that a customer could expect to receive changed material)*

Revision Description:

Initial Release.

Description Of Change:

Die Changes:

1. Elimination of vias by changing Metal 3 interconnect to Metal 2 on the original MMIC layout.
2. Increase some metal widths to meet current handling requirements.

Reason For Change:

To optimize/improve Via robustness to address process package interaction.

Impact of the change (positive or negative) on fit, form, function & reliability:

No change to fit, form, function & reliability.

Summary of Supporting Information:

Qualification has been performed per Industry Standard Test Methods. See attached Qualification Results Summary.

Supporting Documents

Attachment 1: Type: Qualification Results Summary

ADI_PCN_20_0148_Rev_-_Qualification Results Summary_HMC788A Die revision at AEK.pdf

For questions on this PCN, please send an email to the regional contacts below or contact your local ADI sales representatives.

Americas:
PCN_Americas@analog.com

Europe:
PCN_Europe@analog.com

Japan:
PCN_Japan@analog.com

Rest of Asia:
PCN_ROA@analog.com

Appendix A - Affected ADI Models

Added Parts On This Revision - Product Family / Model Number (2)

HMC788A / HMC788ACPSZ-EP-PT

HMC788A / HMC788ACPSZ-EP-R7

Appendix B - Revision History

Rev	Publish Date	Effectivity Date	Rev Description
Rev. -	18-Mar-2020	20-Jun-2020	Initial Release.

Analog Devices, Inc.

DocId:8106 Parent DocId:None Layout Rev:7